

Features

- Advanced Trench MOS Technology
- Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available

Product Summary

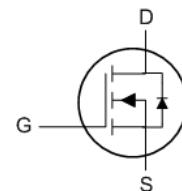
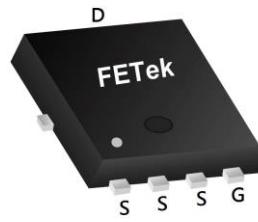


| BVDSS | RDS(ON) | ID |
|-------|---------|-----|
| 30V | 5.5mΩ | 58A |

Application

- Power Management in Desktop Computer.
- DC/DC Converters.

PRPAK5X6 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 30 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ 10V ^{1,6} | 58 | A |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ 10V ^{1,6} | 46 | A |
| I _{DM} | Pulsed Drain Current ² | 125 | A |
| EAS | Single Pulse Avalanche Energy ³ | 48 | mJ |
| I _{AS} | Avalanche Current | 31 | A |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 27 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | --- | 60 | °C/W |
| R _{θJC} | Thermal Resistance Junction-case ¹ | --- | 5.2 | °C/W |



FETek Technology Corp.

FKBA3068

N-Ch 30V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25^\circ C$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------|--|--|------|------|-----------|-----------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 30 | --- | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V, I_D=15A$ | --- | 4 | 5.5 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=15A$ | --- | 6.5 | 8.5 | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=250\mu A$ | 1.2 | 1.7 | 2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=24V, V_{GS}=0V, T_J=25^\circ C$ | --- | --- | 1 | μA |
| | | $V_{DS}=24V, V_{GS}=0V, T_J=55^\circ C$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1MHz$ | --- | 1.8 | --- | Ω |
| Q_g | Total Gate Charge (10V) | $V_{DS}=15V, V_{GS}=10V, I_D=15A$ | --- | 16.5 | --- | nC |
| Q_g | Total Gate Charge (4.5V) | | --- | 8.5 | --- | |
| Q_{gs} | Gate-Source Charge | | --- | 2.9 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 3.5 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$ | --- | 7 | --- | ns |
| T_r | Rise Time | | --- | 42 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 16 | --- | |
| T_f | Fall Time | | --- | 6.2 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=15V, V_{GS}=0V, f=1MHz$ | --- | 882 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 380 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 65 | --- | |

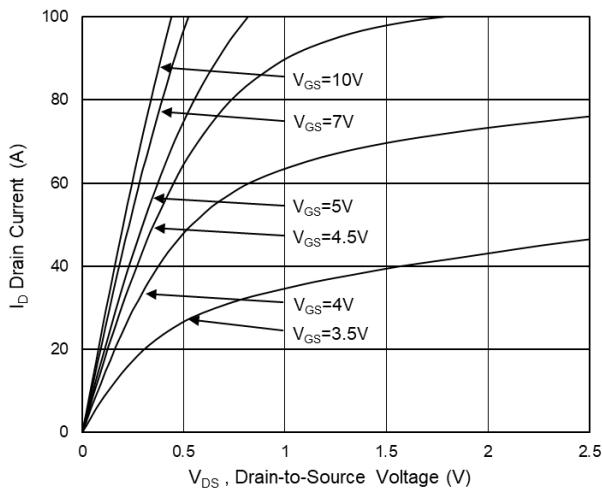
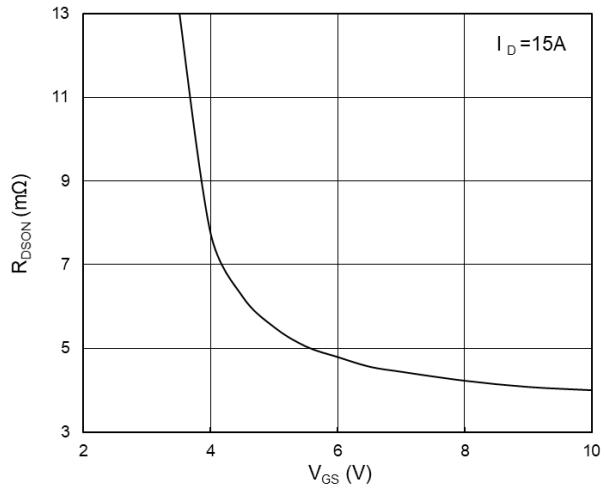
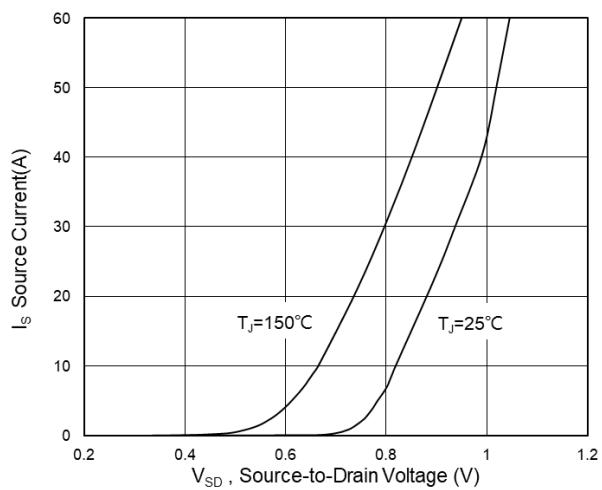
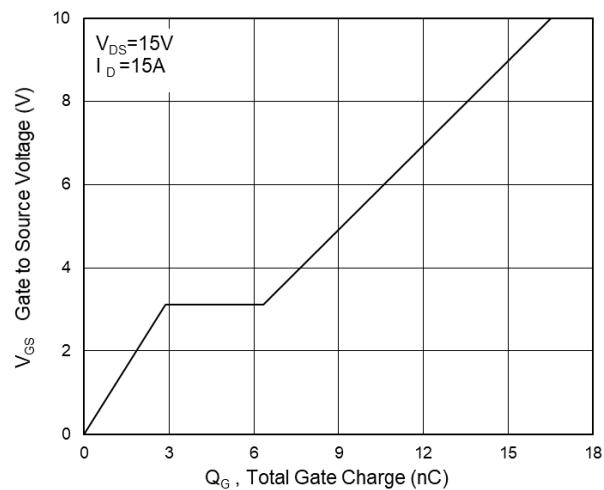
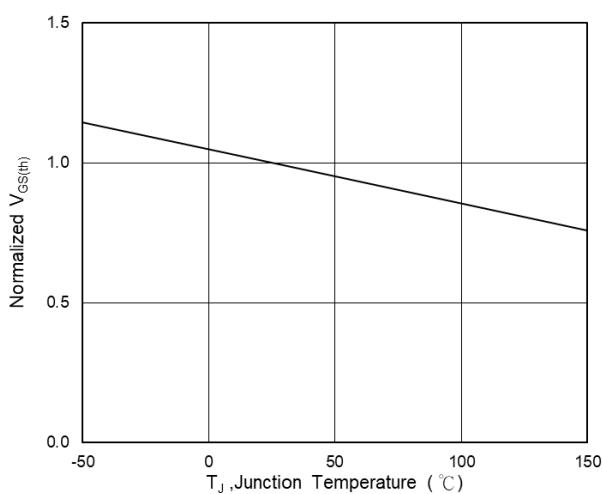
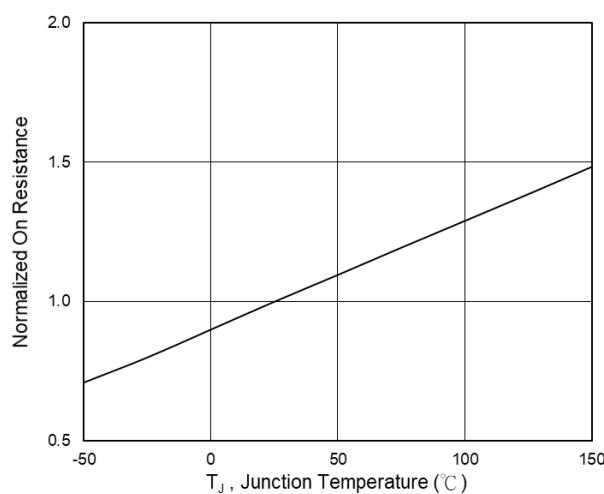
Diode Characteristics

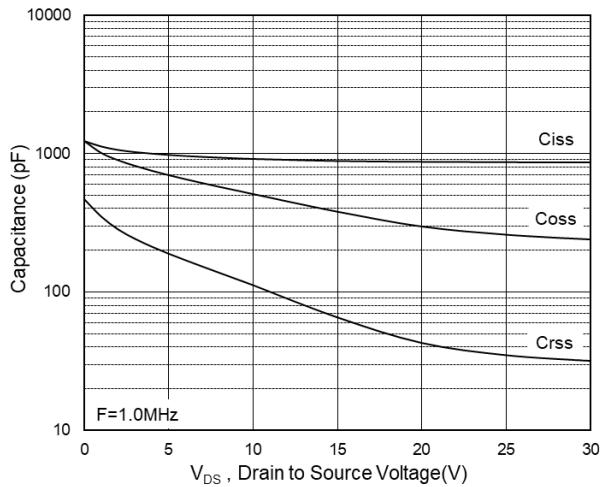
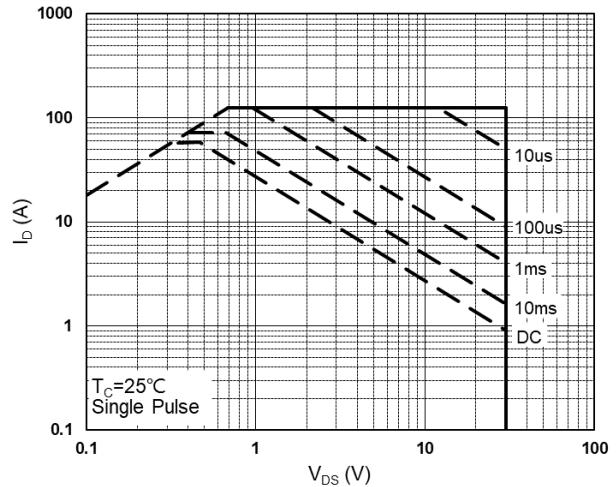
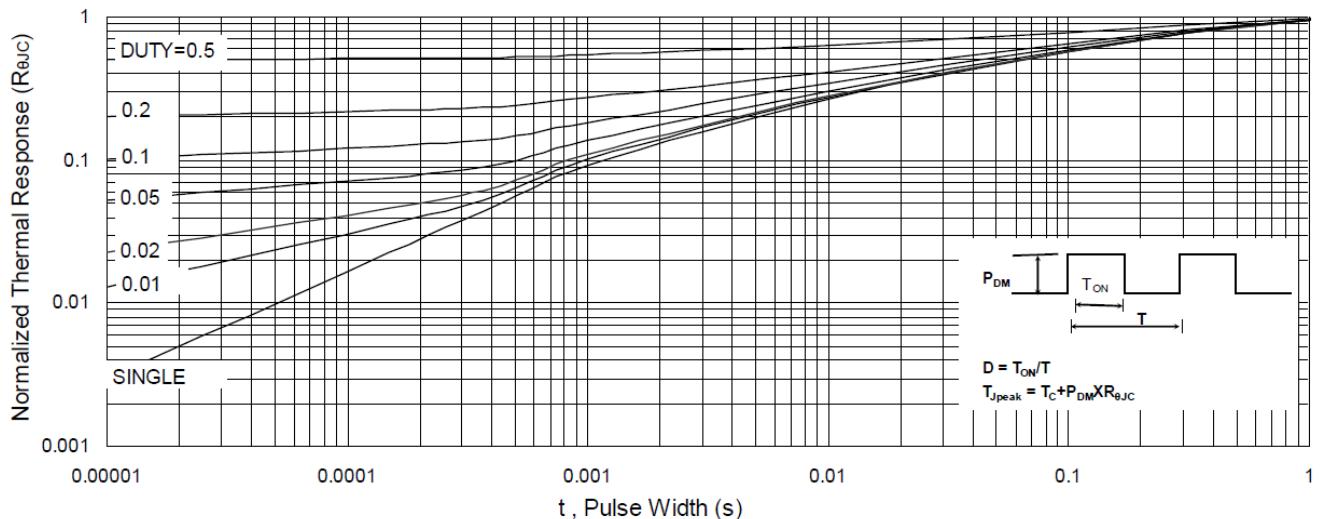
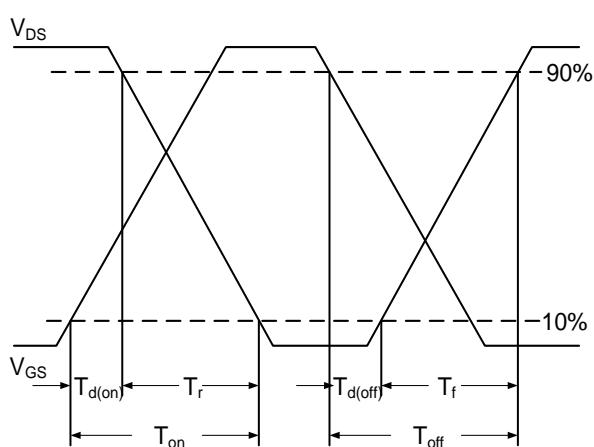
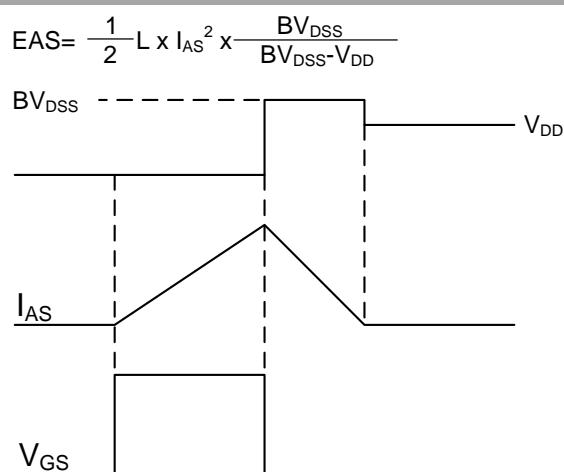
| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--|-------------------------------------|------|------|------|------|
| I_s | Continuous Source Current ^{1,5,6} | $V_G=V_D=0V$, Force Current | --- | --- | 58 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$ | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. Single pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$.
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=31A$
- 4.The power dissipation is limited by $150^\circ C$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform